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V1.0	

# E3272s HiLink Firmware Release Notes

## V1.0

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## Revision Record

Date	Revision version	FW-WebUI/HiLink Version	Change Description	Author
2013-10-28	1.0	FW 22.470.05.00.00 WebUI 13.100.09.00.03		Peng xiaolin

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# E3272s Firmware Release Notes V1.0

## 1 Main Features

The E3272s supports the following standards:

- LTE data service up to 130Mbit/s(Downlink) and 50Mbit/s(Uplink)
- DC-HSPA+ data service up to 43.2 Mbit/s
- HSPA+ data service up to 21.6 Mbit/s
- HSDPA packet data service of up to 14.4 Mbit/s
- HSUPA data service up to 5.76 Mbit/s
- WCDMA PS domain data service of up to 384 Kbit/s
- TD-SCDMA HSUPA data service up to 2.2 Mbit/s
- TD-SCDMA HSDPA data service up to 2.8 Mbit/s
- Equalizer and receive diversity
- microSD Card Slot (Up to 32G)
- Data and SMS Service
- HiLink features (Driverless, WEB UI, Auto connect)
- Plug and play
- Standard USB interface

## 2 Hardware

### 2.1 Hardware Specifications

Item	Specifications
Hardware Version	<ul style="list-style-type: none"><li>● CH2E3272SM</li></ul>
Technical standard	<ul style="list-style-type: none"><li>● LTE 3GPP R9</li><li>● HSPA+/UMTS: 3GPP R99/R5/R6/R7/R8</li><li>● GSM/GPRS/EDGE: 3GPP R99</li></ul>
External interfaces	USB: Type A with standard USB 2.0 High speed interface
	LED: indicating the status of the Data Card
	SD card: standard TF card interface
	SIM/USIM card: standard 6-pin SIM card interface
	RF interface: external RF interface
Maximum power consumption	≤ 3.5 W
Power supply	5V
Dimensions (D × W × H)	About 92mm(D) × 32mm(W) × 14mm (H)



Item	Specifications
Weight	≤ 50 g
Temperature	<ul style="list-style-type: none"><li>Operating: –10°C to +40°C</li><li>Storage: –20°C to +70°C</li></ul>
Humidity	5% to 95%
Base Information	<ul style="list-style-type: none"><li>Plug and play (PnP)</li></ul>
	<ul style="list-style-type: none"><li>Standard USB 2.0 High Speed interface, auto installation, convenient for use</li></ul>
<b>Note:</b> 3GPP = The 3rd Generation Partnership Project TS = Technical Specification LED = Light-Emitting Diode SIM = Subscriber Identity Module USIM = UMTS Subscriber Identity Module	

## 3 Firmware

### 3.1 Version Description

Firmware Version:	22.470.05.00.00
Baseline information	Balong V7R1 C35B270

### 3.2 Firmware Specifications

Firmware		
Item	Specifications	
Version	22.470.05.00.00	
Information	Platform	Balong V7R1
	Baseline	B270
	Feature	LTE Supported
Data service	GSM CS domain	<ul style="list-style-type: none"><li>Uplink: 9.6/14.4 kbit/s</li><li>Downlink: 9.6/14.4 kbit/s</li></ul>
	GPRS	<ul style="list-style-type: none"><li>Uplink: 85.6 kbit/s</li><li>Downlink: 85.6 kbit/s</li></ul>
	EDGE	<ul style="list-style-type: none"><li>Uplink: 236.8 kbit/s</li><li>Downlink: 236.8 kbit/s</li></ul>
	UMTS PS domain	<ul style="list-style-type: none"><li>Uplink: 384 kbit/s</li><li>Downlink: 384 kbit/s</li></ul>
	HSDPA	<ul style="list-style-type: none"><li>14.4Mbit/s</li></ul>



Firmware		
Item	Specifications	
	HSUPA	• 5.76 Mbit/s
	HSPA+	• 21.6Mbit/s
	DC HSPA+	• Uplink:5.76 Mbit/s • Downlink:43.2Mbit/s
	TD-SCDMA	• Uplink:2.2 Mbit/s • Downlink:2.8Mbit/s
	LTE FDD	• Uplink: 50Mbit/s • Downlink:150Mbit/s
	LTE TDD	• Uplink: 10Mbit/s Downlink:112Mbit/s • Uplink: 20Mbit/s Downlink:82Mbit/s
SMS	• SMS over SGs	
Operating System	• Windows XP/Windows Vista/WIN 7/MAC/WIN8	

### 3.3 Improvement in the Previous Version

Index	Case ID	Issue Description

### 3.4 Known Limitations and Issues

Index	Case ID	Issue Description

## 4 WebUI/HiLink

### 4.1 Version Description

WebUI/HiLink Version: 13.100.09.00.03

### 4.2 WebUI/HiLink Specifications

Item	Specifications

### 4.3 Improvement in the Previous Version

Index	Case ID	Issue Description



#### 4.4 Known Limitations and Issues

Index	Case ID	Issue Description
1		NA